



Features

- Low profile package
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- Repetition rate (duty cycle): 0.01%
- Fast response time



SMA
(DO-214AC)

Mechanical Data

- Case: JEDEC DO-214AC/SMA molded plastic body
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbol marking on body
- Mounting Position: Any
- Weight: 0.07 grams

Applications

- I/O interface
- AC/DC power supply
- Low frequency signal transmission line (RS232, RS485, etc.)

Maximum Ratings (Ta=25°C unless otherwise noted)

Peak pulse power dissipation at 10/1000μs waveform (Note1, Note2, Fig.1)	P _{PPM}	400	W
Peak pulse current	I _{PP}	23.5	A
Steady state power dissipation at T _A =50°C (Fig.5)	P _{M(AV)}	3.3	W
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6)	I _{FSM}	60	A
Operating junction and Storage Temperature Range.	T _J , T _{STG}	-65 to +150	°C
Typical thermal resistance junction to lead	R _{θJL}	30	°C/W
Typical thermal resistance junction to ambient	R _{θJA}	120	°C/W

Notes:1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25°C per Fig.2.

2. Mounted on 5.0mm×5.0mm (0.03mm thick) copper pads to each terminal.

3. 8.3ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.

Electrical Characteristics (T_A =25°C)

Part Number		Device Marking Code		Reverse Stand- Off Voltage	Breakdown Voltage @I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _{RWM}
Unidirectional	Bidirectional	UNI	BI	V _{RWM} (V)	V _{BR} (V)	I _T (mA)	V _C (V)	I _{PP} (A)	I _R (μA)
SZ1SMA10AT3G	SZ1SMA10CAT3G	AX	WX	10.0	11.1-12.3	1	17.0	23.5	5

